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(12) **United States Design Patent**
Podubni

(10) **Patent No.:** **US D826,186 S**

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- (54) **MODULAR CIRCUIT BOARD**
- (71) Applicant: **Tiny PCB, Inc.**, San Jose, CA (US)
- (72) Inventor: **Edward Podubni**, San Jose, CA (US)
- (73) Assignee: **TinyPCB, Inc.**
- (**) Term: **15 Years**
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- (22) Filed: **May 26, 2017**
- (51) **LOC (11) Cl.** **13-03**
- (52) **U.S. Cl.**
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- (58) **Field of Classification Search**
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361/720, 728, 736, 748, 751, 752, 760,
361/761, 807; 439/55, 65, 68, 76.1, 92,
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- CPC H05K 3/00; H05K 3/30; H05K 3/301; H05K
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- See application file for complete search history.

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Primary Examiner — Elizabeth J Oswecki
(74) *Attorney, Agent, or Firm* — Cooley LLP

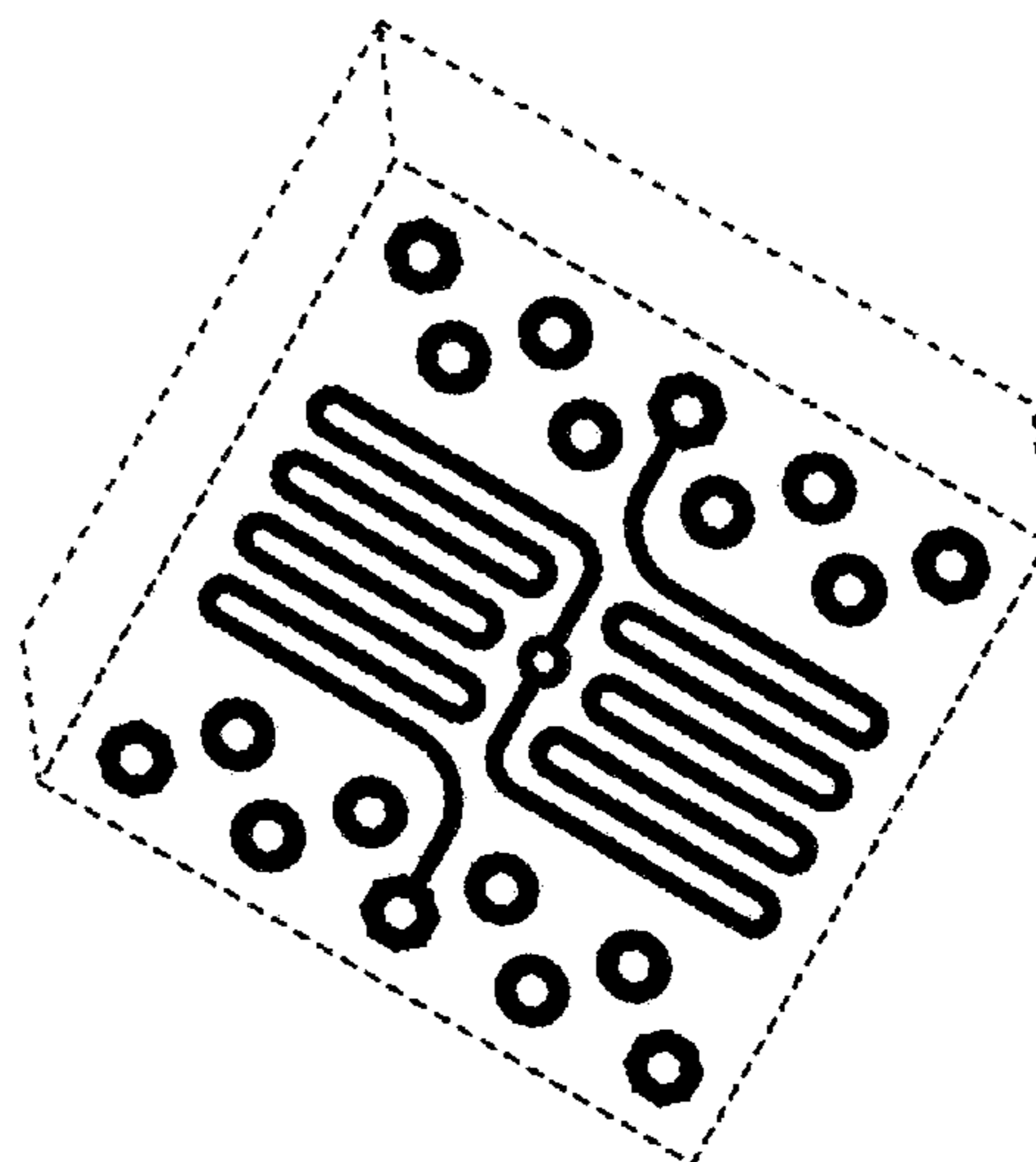
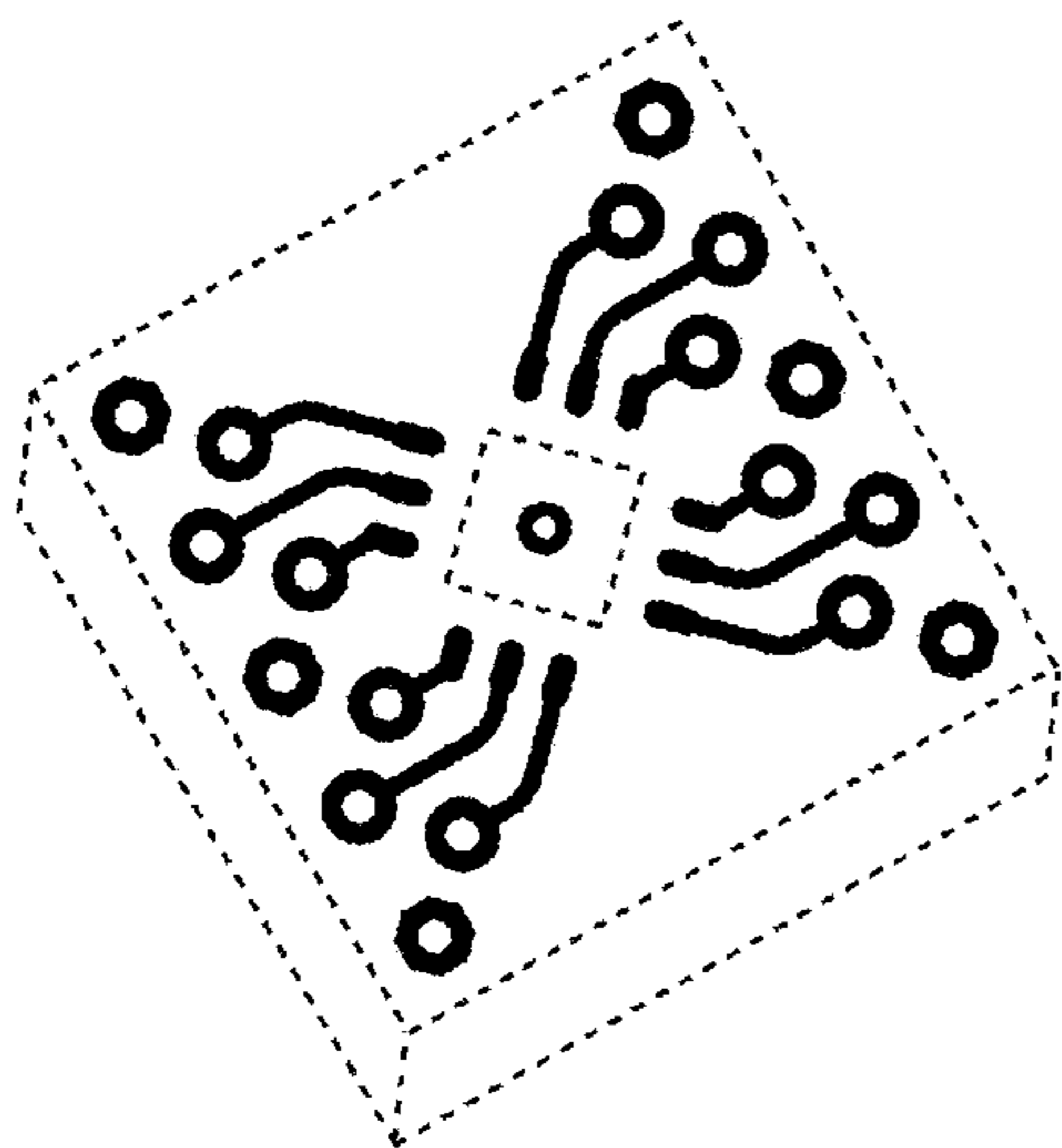
(57) **CLAIM**

The ornamental design for a modular circuit board, as shown and described.

DESCRIPTION

FIG. 1 is a top perspective view of a modular circuit board, showing my new design;
FIG. 2 is a bottom perspective view thereof;
FIG. 3 is a top view thereof;
FIG. 4 is a bottom view thereof; and,
FIG. 5 is a side view thereof, all other side views being a mirror image thereof.
The broken lines shown in the drawings represent portions of the modular circuit board that form no part of the claimed design.

1 Claim, 5 Drawing Sheets



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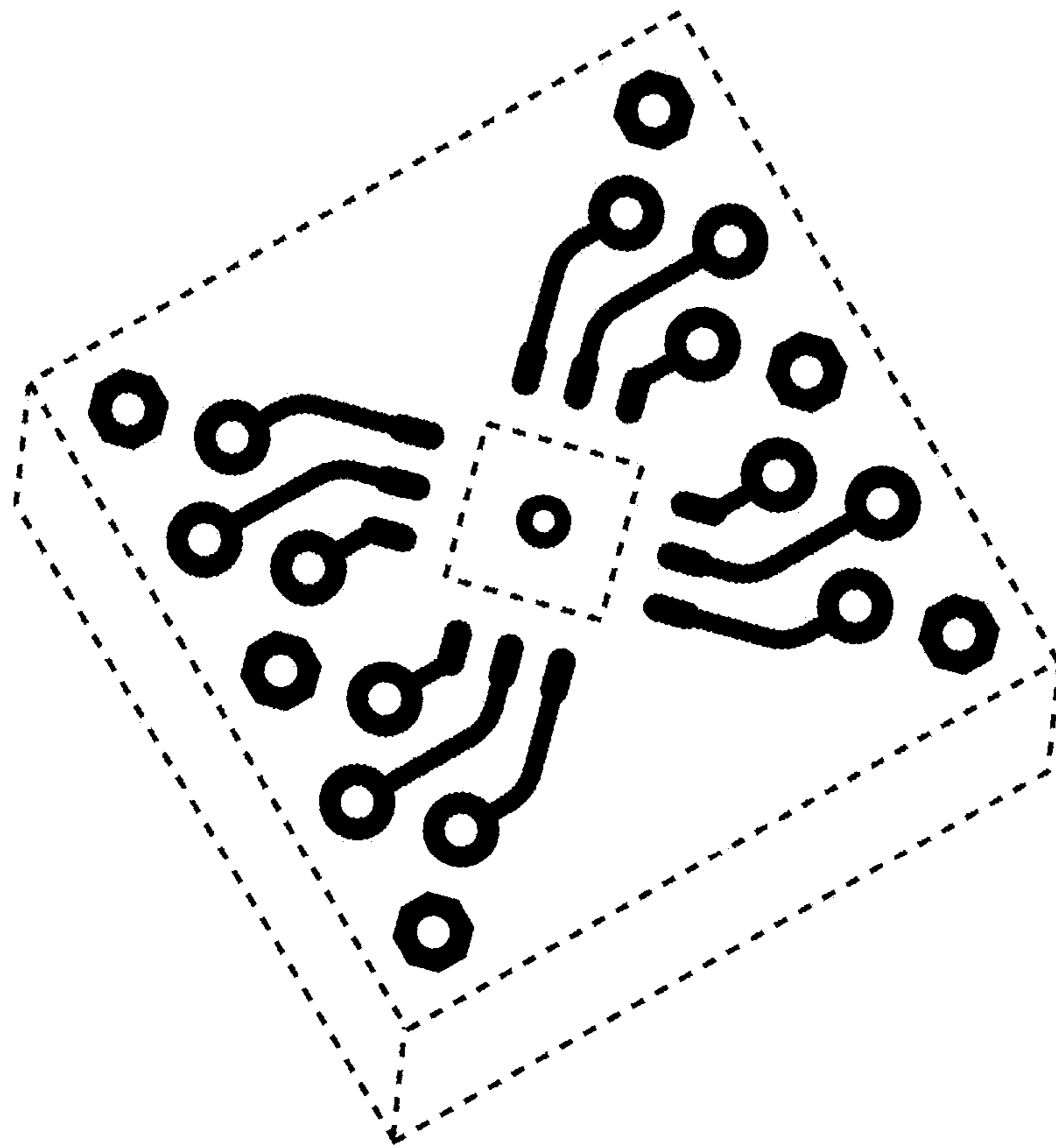


FIG. 1

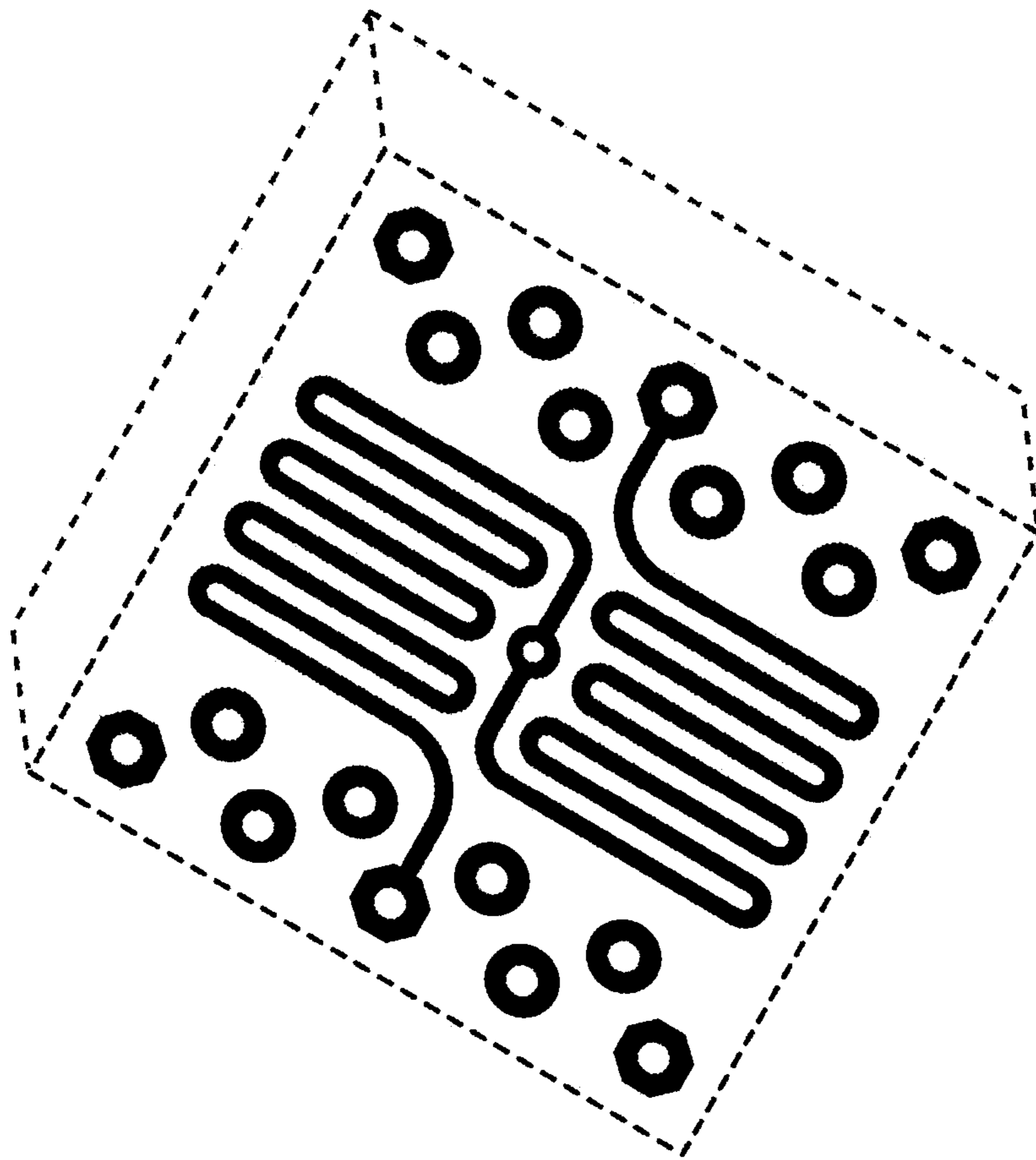


FIG. 2

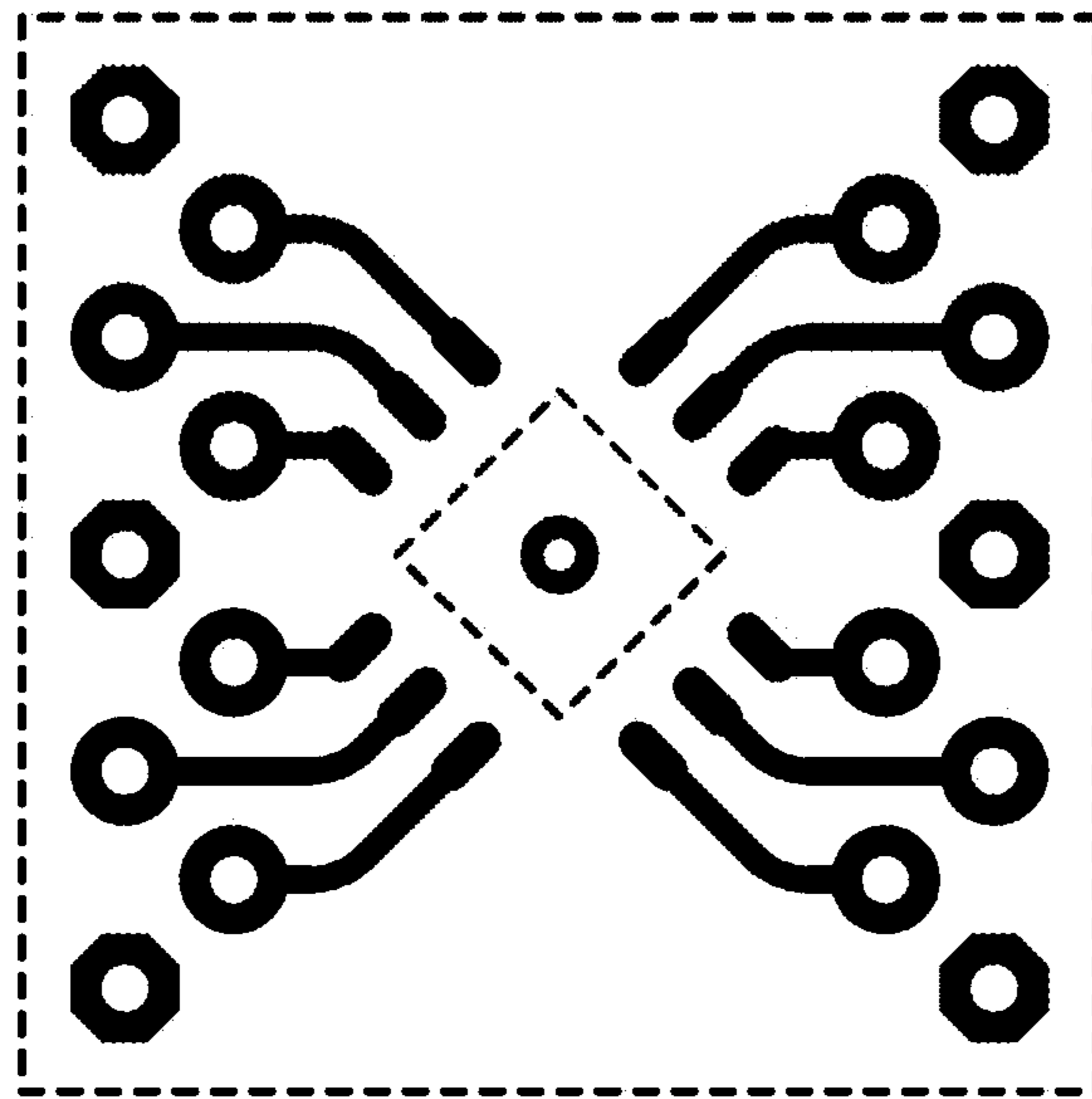


FIG. 3

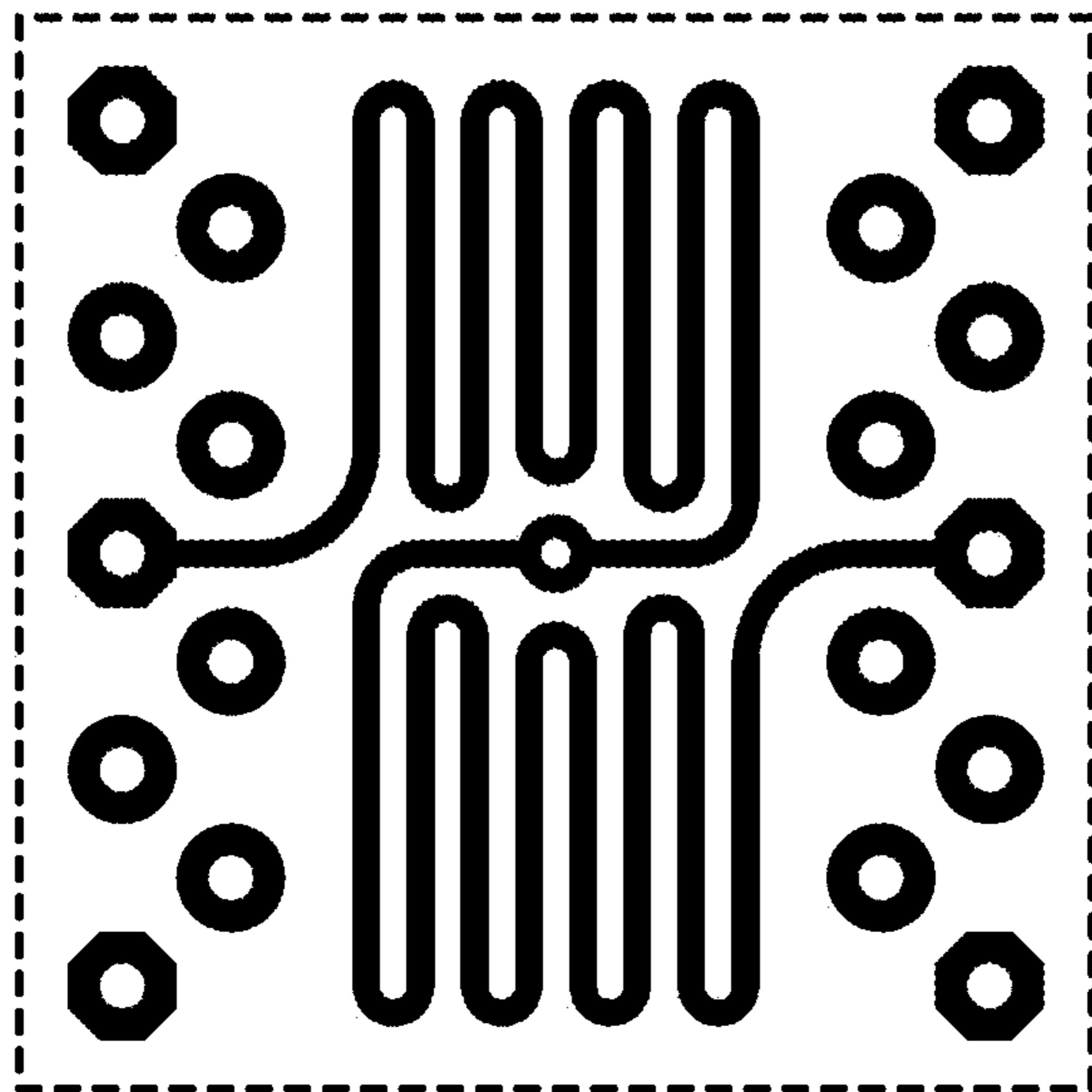


FIG. 4



FIG. 5